

Specifications

Mechanics

<i>X, Y table</i>	Working area 100 x 115 mm Resolution 0.25 µm, repeatability < 2 µm
<i>Z-axis</i>	60 mm
<i>Speed</i>	up to 20 wires / min.
<i>Bond head</i>	Gold Ball-Wedge Negative flame-off unit F & K 67 kHz US standard, 120 kHz or 140 kHz optional Wire diameter 17.5 ... 50 µm

Control

<i>Heating</i>	Integrated in machine 0-250°C
<i>Computer</i>	Dual Core PC, 1,6 GHz Processor, 4 GB RAM, Ethernet, USB 4x + 4x frontside
<i>Monitor</i>	TFT flat screen
<i>Operation system</i>	Windows 7
<i>Printer</i>	All Windows-compatible printers can be installed All bonding parameters can be printed
<i>Heated work holder</i>	Standard 4x4" optional Ø 80mm (Attention: 4x4" up to 200°C; 80 mm up to 250°C)

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Other features

<i>Programming</i>	Automatic bonding of hybrids or COB with programmable X/Y table
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5610

Semi-automatic Gold Ball Bonder

The semi-automatic Gold Ball Bonder 5610 fills the gap between the manual and semi-automatic Ball Bonder. The 5610 is fully PC controlled and allows any number of bonds and bumps to be programmed. Pre-programmed adjust points are targeted through the camera's cross hair targeting system and the programmed bonds or bumps are executed automatically. Two operating modes are available: Single bond for repair of various bond samples and making single bonds (manual-automatic) and multi wire for teaching and bonding chips or various bond samples (semi and fully automatic).

The 5610 can also be used as Thin Wire Wedge Wedge or Heavy Wire as well as pull-/shear tester by simply replacing the bond head and loading the appropriate software. Set-up time: approx. 5 minutes.

Ask us for more information.

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Work holders

Standard



optional



For components up to 4 x 4"

For components up to \varnothing 80

mm

mechanical clamping + Vacuum
un-/heated

Vacuum and mechanical clamping
un-/heated

Head Parking System For storing of temporary not required bondhead or pull- and shear-heads.
Can be mounted on the left or right side of the machine

General

Camera With cross hair targeting for positioning of bonds

Microscope Stereoskop Standard 40x, other Microscopes optional

Lighting 20 W halogen spot light and LED direct light, incident light, ringlight and spotlight programmable

Dimensions Height 70 cm, width 70 cm, depth 65 cm; approx. 70 kg

Supplies 100...240 VAC, single-phase, 50/60 Hz, max. 500 VA;

Connections Air 6 bar; vacuum 0,7 bar